

IN THE CLAIMS

Please cancel claims ~~29, 30 and 32-38~~. Please amend claims 1, 5-9, 16, 23, 27, 28, 31 and 32 as follows:

A2
1. (Amended) A particle dispersion comprising a liquid and a collection of particles at a concentration of less than about 50 weight percent in the dispersion, the collection of particles having an average primary particle diameter less than about [100] 50 nm and [effectively no particles] less than about one in 10⁶ particles having a primary particle diameter greater than about three times the average primary particle diameter.

5. (Amended) The particle dispersion of claim 1 [wherein the solvent has] having a pH less than about 4 pH units.

A3
6. (Amended) The particle dispersion of claim 1 [wherein the solvent has] having a pH less than about 3 pH units.

7. (Amended) The particle dispersion of claim 1 [wherein the solvent has] having a pH greater than about 9 pH units.

8. (Amended) The particle dispersion of claim 1 [wherein the solvent has] having a pH from about 9 pH units to about 11 pH units.

9. (Amended) The particle dispersion of claim 1 [wherein the solvent has] having a pH from about 6 pH units to about 8 pH units.

A4
16. (Amended) The particle dispersion of claim 15 wherein the organic liquid is selected from the group consisting of alcohols, acetone, and carboxylic acids.

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23. (Amended) The particle dispersion of claim 1 wherein the collection of particles [effectively having no] has less than about one in 10⁶ particles with a primary particle diameter greater than about two times the average primary particle diameter.

A6
27. (Amended) The method of claim 26 wherein the surface comprises a plurality of compositions and wherein the dispersion has a selective removal upon abrading of the surface with the removal rate of one surface composition being at least about 5 times greater than the removal rate of another surface composition.

28. (Amended) A method for forming a particle dispersion, the method comprising mixing a collection of particles with a liquid, the collection of particles having an average primary particle diameter from about 5 nm to about 50 nm and [effectively no particles] less than about one in 10⁶ particles having a primary particle diameter greater than about three times the average primary particle diameter.

31. (Amended) A method for polishing a surface comprising metal or a metal compound, the method comprising:

abrading the surface with a particle dispersion, the particle dispersion comprising a collection of particle having an average primary particle diameter less than about [100] 50 nm, [the abrasion removing] abrading the surface results in removal of greater than about a factor of two more material from the surface per unit time than corresponding polishing with an equivalent concentration of particles having an equivalent composition and an average particle diameter of greater than about 1 micron.

REMARKS

Claims 1-28 and 31 remain for consideration. Claims 29, 30 and 32-38 have been canceled without prejudice. Claims 5-9, 16, 27 and 28 have been amended for clarity. Claims 1, 23, 28 and 31 have been amended to more particularly point out Applicants claimed invention. The amendment to claim 1 is supported by the specification, for example, at page 36, lines 1-2 and page 38, lines 11-15. The amendments to claims 23 and 28 are supported by the specification, for example, at page 38, lines 11-15. The amendment to claim 31 is supported by the specification, for example, at page 36, lines 1-2 and page 51, lines 18-27. No new matter is introduced by the amendments.

Applicants respectfully request reconsideration of the rejection of the pending claims in view of the following comments.